# **CMOS SSI**

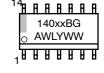
# Quad Exclusive "OR" and "NOR" Gates

The MC14070B quad exclusive OR gate and the MC14077B quad exclusive NOR gate are constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. These complementary MOS logic gates find primary use where low power dissipation and/or high noise immunity is desired.

- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- · All Outputs Buffered
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load Over the Rated Temperature Range
- Double Diode Protection on All Inputs
- MC14070B Replacement for CD4030B and CD4070B Types
- MC14077B Replacement for CD4077B Type
- Pb-Free Packages are Available



SOIC-14 **D SUFFIX** 



### MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>)

Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage Range	-0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage Range (DC or Transient)	−0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient) per Pin	±10	mA
P <sub>D</sub>	Power Dissipation, per Package (Note 1)	500	mW
T <sub>A</sub>	Ambient Temperature Range	-55 to +125	°C
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8-Second Soldering)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, Vin and Vout should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V<sub>SS</sub> or V<sub>DD</sub>). Unused outputs must be left open.



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#### **MARKING DIAGRAMS**



PDIP-14 **P SUFFIX CASE 646** 

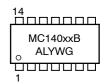




CASE 751A



SOEIAJ-14 **F SUFFIX CASE 965** 

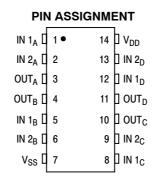


= Specific Device Code XX = Assembly Location

WL. L = Wafer I ot = Year YY. Y ww w = Work Week = Pb-Free Package

## ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.



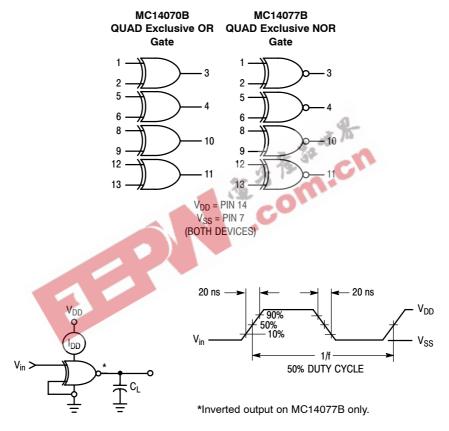
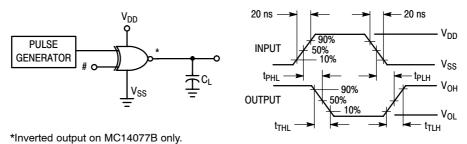


Figure 1. Power Dissipation Test Circuit and Waveform



#Connect unused input to  $V_{DD}$  for MC14070B, to  $V_{SS}$  for MC14077B.

Figure 2. Switching Time Test Circuit and Waveforms

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>	
MC14070BCP	PDIP-14	25 Units / Rail	
MC14070BCPG	PDIP-14 (Pb-Free)		
MC14070BD	SOIC-14		
MC14070BDG	SOIC-14 (Pb-Free)	55 Units / Rail	
MC14070BDR2	SOIC-14		
MC14070BDR2G	SOIC-14 (Pb-Free)	2500 / Tape & Reel	
MC14070BFEL	SOEIAJ-14		
MC14070BFELG	SOEIAJ-14 (Pb-Free)	2000 / Tape & Reel	
MC14077BCP	PDIP-14		
MC14077BCPG	PDIP-14 (Pb-Free)	25 Units / Rail	
MC14077BD	SOIC-14	* 15-	
MC14077BDG	SOIC-14 (Pb-Free)	55 Units / Rail	
MC14077BDR2	SOIC-14	*	
MC14077BDR2G	SOIC-14 (Pb-Free)	2500 / Tape & Reel	
MC14077BFEL	SOEIAJ-14		
MC14077BFELG	SOEIAJ-14 (Pb-Free)	2000 / Tape & Reel	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

				- 55	5°C	25°C			125°C		
Characteristic	:	Symbol	V <sub>DD</sub> Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	"0" Level	V <sub>OL</sub>	5.0 10 15	- - -	0.05 0.05 0.05		0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
V <sub>in</sub> = 0 or V <sub>DD</sub>	"1" Level	V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	"0" Level	V <sub>IL</sub>	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V <sub>IH</sub>	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	- - -	Vdc
Output Drive Current $ (V_{OH} = 2.5 \text{ Vdc}) $ $ (V_{OH} = 4.6 \text{ Vdc}) $ $ (V_{OH} = 9.5 \text{ Vdc}) $ $ (V_{OH} = 13.5 \text{ Vdc}) $	Source	Іон	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	- - -	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	- - -	- 1.7 - 0.36 - 0.9 - 2.4	- - -	mAdc
(V <sub>OL</sub> = 0.4 Vdc) (V <sub>OL</sub> = 0.5 Vdc) (V <sub>OL</sub> = 1.5 Vdc)	Sink	I <sub>OL</sub>	5.0 10 15	0.64 1.6 4.2	海	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current		I <sub>in</sub>	15		± 0.1	_	±0.00001	± 0.1	-	± 1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)		C <sub>in</sub>	•	-	_	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)	1	I <sub>DD</sub>	5.0 10 15	- - -	0.25 0.5 1.0	- - -	0.0005 0.0010 0.0015	0.25 0.5 1.0	- - -	7.5 15 30	μAdc
Total Supply Current (Notes (Dynamic plus Quiescer Per Package) (C <sub>L</sub> = 50 pF on all outpu buffers switching)	nt,	I <sub>T</sub>	5.0 10 15			$I_T = (0$	).3 μΑ/kHz) † ).6 μΑ/kHz) † ).9 μΑ/kHz) †	f + I <sub>DD</sub>			μAdc
Output Rise and Fall Times $(C_L = 50 \text{ pF})$ $t_{TLH}, t_{THL} = (1.35 \text{ ns/pF}) (1.35 $	C <sub>L</sub> + 33 ns C <sub>L</sub> + 20 ns	t <sub>TLH</sub> , t <sub>THL</sub>	5.0 10 15	- - -	- - -	- - -	100 50 40	200 100 80	- - -	- - -	ns
Propagation Delay Times (N (C <sub>L</sub> = 50 pF) t <sub>PLH</sub> , t <sub>PHL</sub> = (0.90 ns/pF) C t <sub>PLH</sub> , t <sub>PHL</sub> = (0.36 ns/pF) C t <sub>PLH</sub> , t <sub>PHL</sub> = (0.26 ns/pF) C	$C_L + 130  \text{ns}$ $C_L + 57  \text{ns}$ $C_L + 37  \text{ns}$	t <sub>PLH</sub> , t <sub>PHL</sub>	5.0 10 15	- - -	- - -	- - -	175 75 55	350 150 110	- - -	- - -	ns

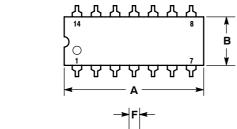
Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

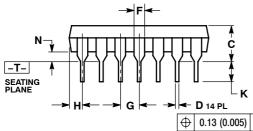
$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

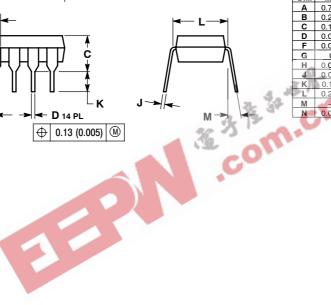
where:  $I_T$  is in  $\mu H$  (per package),  $C_L$  in pF, V = ( $V_{DD} - V_{SS}$ ) in volts, f in kHz is input frequency, and k = 0.002.

# **PACKAGE DIMENSIONS**

PDIP-14 CASE 646-06 ISSUE P





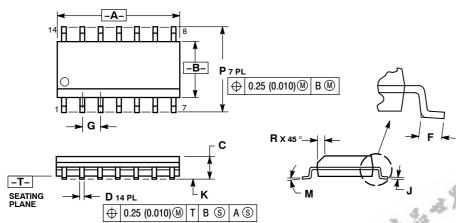


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.715	0.770	18.16	19.56		
В	0.240	0.260	6.10	6.60		
С	0.145	0.185	3.69	4.69		
D	0.015	0.021	0.38	0.53		
F	0.040	0.070	1.02	1.78		
G	0.100	BSC	2.54 BSC			
H_	0.052	0.095	1.32	2.41		
d d	0.008	0.015	0.20	0.38		
K	0.115	0.135	2.92	3.43		
≥L.	0.290	0.310	7.37	7.87		
M	-	10 °		10 °		
N	0.015	0.039	0.38	1.01		

# **PACKAGE DIMENSIONS**

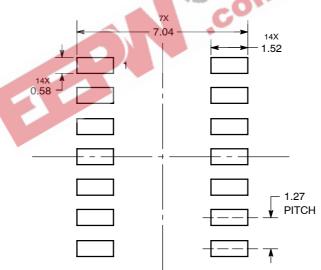
SOIC-14 CASE 751A-03 **ISSUE H** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
- 1. DIMENSIONING AND TOLEHANGING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- 4. MAXIMUM MOLD PROTRUSION 0.15 (0.0) PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION, ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	8.55	8.75	0.337	0.344	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
_K	0.10	0.25	0.004	0.009	
M	0 °	7 °	0 °	7°	
P	5.80	6.20	0.228	0.244	
R	0.25	0.50	0.010	0.019	

# SOLDERING FOOTPRINT

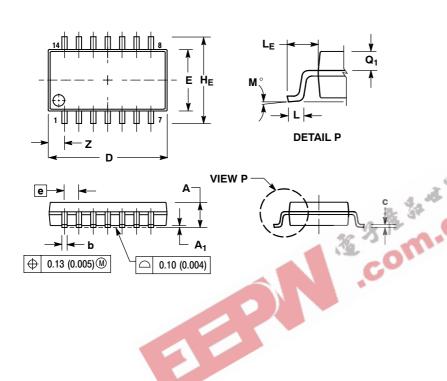


DIMENSIONS: MILLIMETERS

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

SOEIAJ-14 CASE 965-01 ISSUF A



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION: MILLIMETER
- 2. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α		2.05	-	0.081	
A <sub>1</sub>	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
C	0.10	0.20	0.004	0.008	
D	9.90	10.50	0.390	0.413	
Е	5.10	5.45	0.201	0.215	
е	1.27	BSC	0.050 BSC		
HE	7.40	8.20	0.291	0.323	
0.50	0.50	0.85	0.020	0.033	
LE	1.10	1.50	0.043	0.059	
M	0 °	10°	0°	10°	
Q <sub>1</sub>	0.70	0.90	0.028	0.035	
Z		1.42		0.056	

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